onsemi

Schottky Barrier Diode NSR20F20NXT5G

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current and are offered in a Chip Scale Package (CSP) to reduce board space. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

Features

- Low Forward Voltage Drop 450 mV @ 2.0 A
- Low Reverse Current 30 µA @ 10 V VR
- 2.0 A of Continuous Forward Current
- Power Dissipation of 665 mW with Minimum Trace
- ESD Rating Human Body Model: Class 3B – Machine Model: Class C
- High Switching Speed
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

Markets

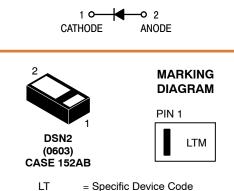
- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Reverse Voltage		V _R	20	V
Forward Current (DC)		١ _F	2.0	А
Forward Surge C cycle)	current (60 Hz @ 1	I _{FSM}	28	А
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)		I _{FRM}	4.0	A
ESD Rating:	Human Body Model Machine Model	ESD	> 8 > 400	kV V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.





= Month Code

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ORDERING INFORMATION

Device	Package	Shipping†
NSR20F20NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NSR20F20NXT5G

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ $T_A = 25^{\circ}C$	R _{θJA} P _D			213 586	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA} PD			80 1.56	°C/W W
Storage Temperature Range	T _{stg}			-40 to +125	°C
Junction Temperature	TJ			+150	°C

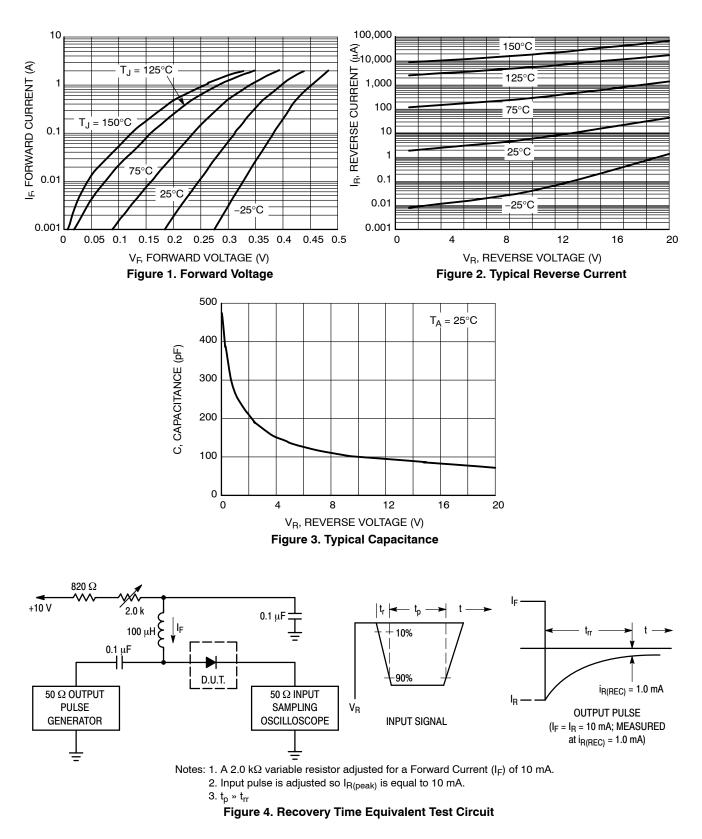
Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage $(V_R = 10 \text{ V})$ $(V_R = 20 \text{ V})$	I _R			30 150	μΑ
Forward Voltage (I _F = 1.0 A) (I _F = 2.0 A)	V _F		0.390 0.450	0.420 0.470	V
Reverse Recovery Time ($I_F = I_R = 10 \text{ mA}, I_{R(REC)} = 1.0 \text{ mA}, Figure 4$)	t _{rr}		80		ns

NSR20F20NXT5G

TYPICAL CHARACTERISTICS





DSN2, 1.6x0.8, 0.9P, (0603) CASE 152AB **ISSUE C** DATE 30 APR 2017 SCALE 8:1 NOTES: 1. DIMENSIONING AND TOLERANCING PER \Box 0.05 C ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. AB D ->-MILLIMETERS DIM MIN MAX A 0.25 0.31 Ε A1 0.05 **b** 0.55 0.65 A \Box 0.05 C D 1.60 BSC TOP VIEW F 0.80 BSC L 1.45 1.55 L2 0.90 1.00 // 0.05 C L3 0.25 0.35 Α GENERIC \square 0.05 C GENERIC Α1 **MARKING DIAGRAM2*** SEATING PLANE **MARKING DIAGRAM1*** С PIN 1 PIN 1 SIDE VIEW XXXX XXM ⊕ 0.05 C A B . . . YYY XX = Specific Device Code XXXX = Specific Device Code L/2 b M = Date Code YYY = Year Code *This information is generic. Please refer \oplus 0.05 C A B to device data sheet for actual part 2 marking. Pb-Free indicator, "G", may L3 or not be present. Some products may not follow the Generic Marking. **BOTTOM VIEW** CATHODE BAND MONTH CODING **MOUNTING FOOTPRINT*** NOV OCT DEC 70 9 SFF 0.52 0.80 **DEVICE CODE** 000 JUN 000 PIN 1 YEAR CODE MAR 0.70 FEB-1 05 JAN 600 DIMENSIONS: MILLIMETERS XXXX See Application Note AND8464/D for more mounting details lo⊟o (EXAMPLE) *For additional information on our Pb-Free strategy and soldering 000 Y09 details, please download the onsemi Soldering and Mounting 000 Techniques Reference Manual, SOLDERRM/D. **INDICATES AUG 2009**

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